

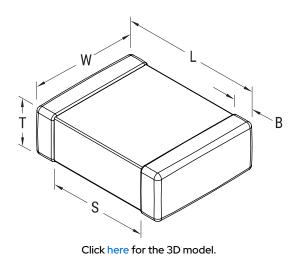
## C1812C333MATACTU

Aliases (C1812C333MATAC7800)

**Specifications** 

Insulation Resistance

SMD Comm X8G HT150C, Ceramic, 0.033 uF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

••	0.2 / 0.0
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm
Packaging Specifications	

	Capacitance	0.033 uF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	20%
	Voltage DC	250 VDC
	Dielectric Withstanding Voltage	625 VDC
	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

30.303 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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